Micro-Abrasive Blasting
Solutions for the Semiconductor Industry

Probe Rings
Silicon Wafers
Integrated Circuit Packaging
Microfluidics
Inkjet Printer Heads
Wire Bonding Tools
Insulators

Precision and Control for Delicate Applications

Micro-abrasive blasting is an effective process for cutting, cleaning, deburring, and texturing wafers and delicate components. Comco’s AccuFlo offers the control necessary to process parts effectively without risk of damage to underlying substrates or delicate circuitry.

Our micro-abrasive blasters delivers pinpoint accuracy for cutting slots, holes and micro-grooves in thin fragile substrates. The process is effective for bevelling edges of silicon power devices to expose junction, or carefully removing diffusion mask residue and metalization layers on wafers.

Texturing the surface of component parts improves adhesion for bonding and increases the peel strength of the material when attached to other substrates. Blasting works effectively on the surface of either rigid or flexible substrate materials.

This process is used to safely remove oxidation, residue, discoloration and surface defects without altering surface component properties. It can also be used to drill holes for micro-fluidics applications.
Applications in the Semiconductor Industry

**Probe Rings**
Trim epoxy to reduce risk of damage to probes safely. Minimal operator training required.

**Wire Bonding Tools**
Improve wire feeding through small capillary tip openings by blasting to remove fine burrs.

**Integrated Circuit Packaging**
Remove machining marks and deburr pin grid arrays without causing dimensional changes.

**Inkjet Printer Heads**
Cut or drill precise slots without causing property changes to the wafer.

**Ceramic components**
Remove oxides, metallization, and other contaminants on delicate ceramic parts.

**Silicon Wafers**
Bevel wafer edges and remove diffusion mask residues quickly.

**Automated Solutions for Increased Production**
For more than 45 years Comco’s engineers have integrated up to four axis of motion, multiple nozzles, conveyors, and powerful blasters into automated equipment. If your application requires greater production capabilities than a manual blasting system provides, contact us today.

**Comco’s Applications Lab**
Comco’s Applications Engineers have the expertise and complete test facilities to determine if a micro-abrasive blasting process can improve your production efficiency and product quality.

Contact us today at 800-796-6626
And discover the MicroBlasting solution to your production problems!

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